

Part Number: KB-2885CGKD

Green

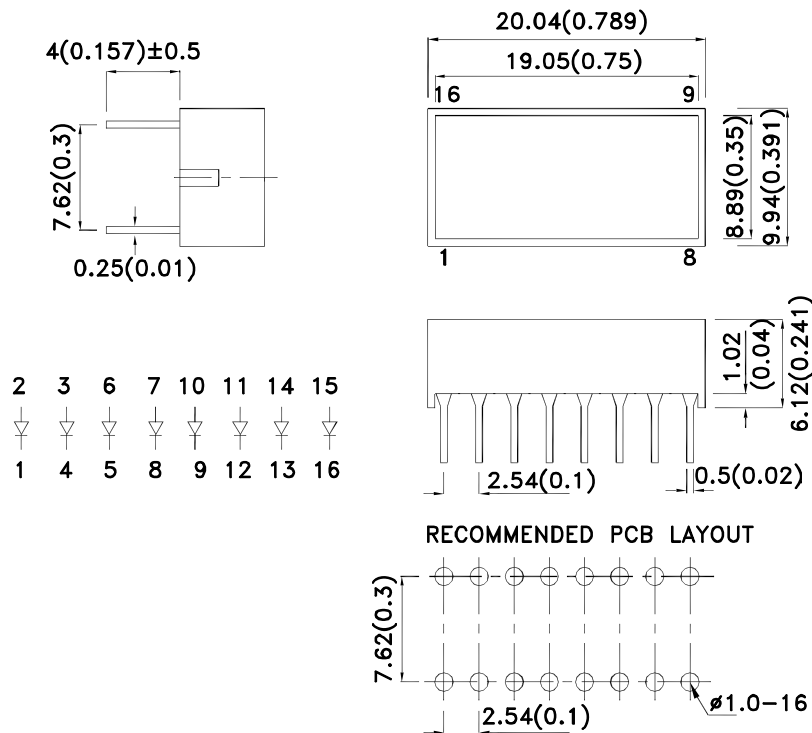
### Features

- Uniform light emitting area.
- Low current operation.
- Easily mounted on P.C. boards.
- Flush mountable.
- Excellent on/off contrast.
- Can be used with panels and legend mounts.
- RoHS compliant.

### Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

### Package Dimensions & Internal Circuit Diagram



**Notes:**

1. All dimensions are in millimeters (inches), Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [1] @ 20mA	
			Min.	Typ.
KB-2885CGKD	Green (AlGaInP)	Green Diffused	40	59

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	Green	574		nm	I <sub>F</sub> =20mA
$\lambda_D$ [1]	Dominant Wavelength	Green	570		nm	I <sub>F</sub> =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	Green	20		nm	I <sub>F</sub> =20mA
C	Capacitance	Green	15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Green	2.1	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	Green		10	uA	V <sub>R</sub> =5V

Notes:

1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	150	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

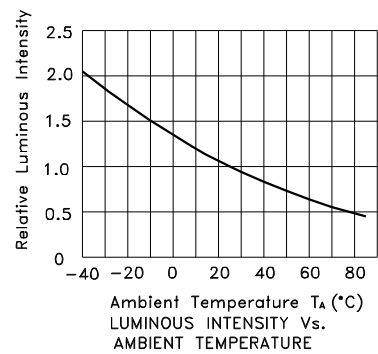
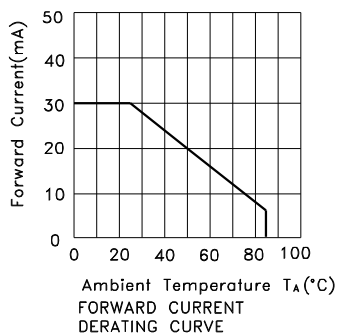
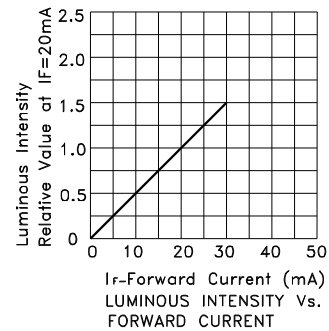
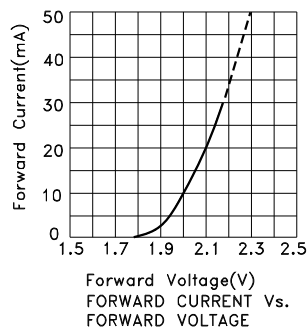
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.

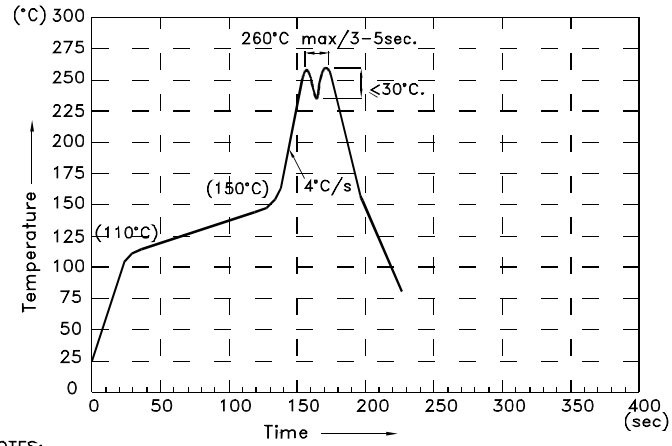


## Green

### KB-2885CGKD



Wave Soldering Profile For Lead-free Through-hole LED.

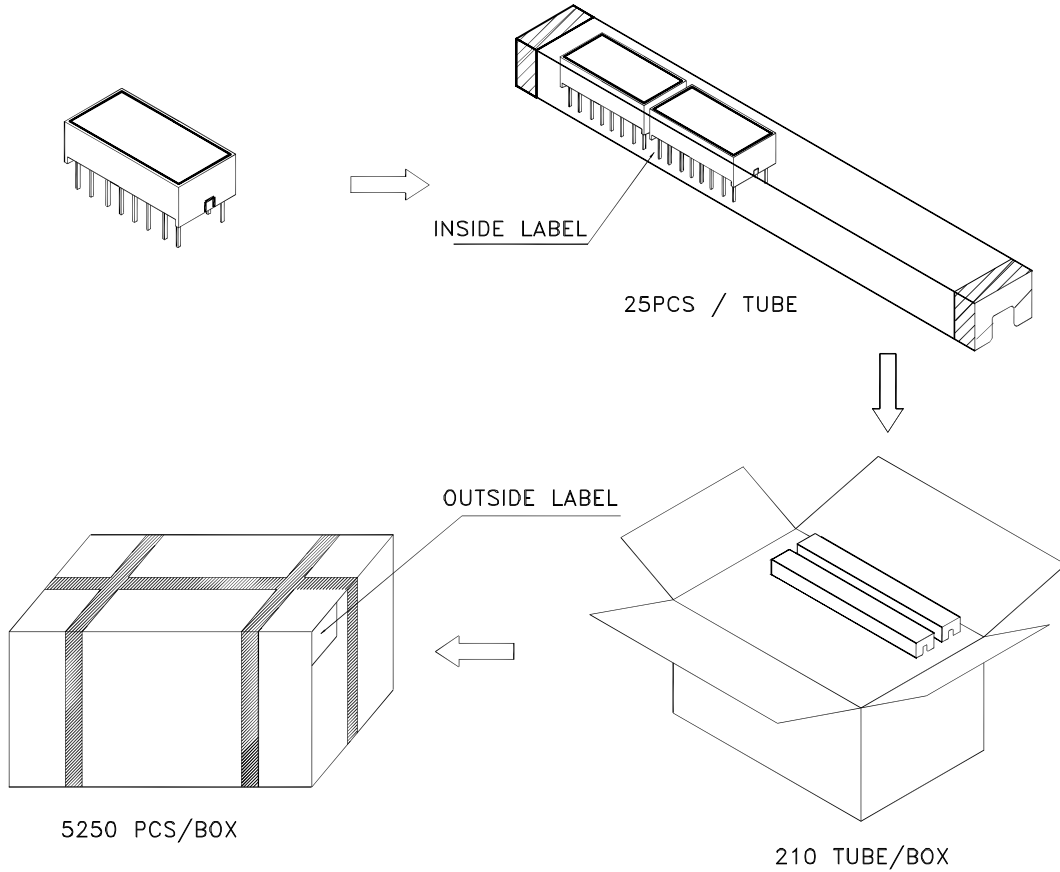


NOTES:

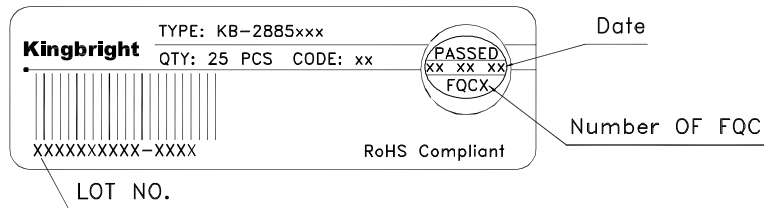
- 1.Recommend the wave temperature 245°C~260°C.The maximum soldering temperature should be less than 260°C.
- 2.Do not apply stress on epoxy resins when temperature is over 85°C.
- 3.The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
- 4.During wave soldering, the PCB top-surface temperature should be kept below 105°C.
- 5.No more than once.

## PACKING & LABEL SPECIFICATIONS

## KB-2885CGKD



Inside Label On IC-tube



Outside Label On Box

